

OL-PCT2202

wafer level chip-scale package; 6 bumps; 0.69 x 1.09 x 0.38 mm (Backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP6
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-11-2014

Table 1. Package summary

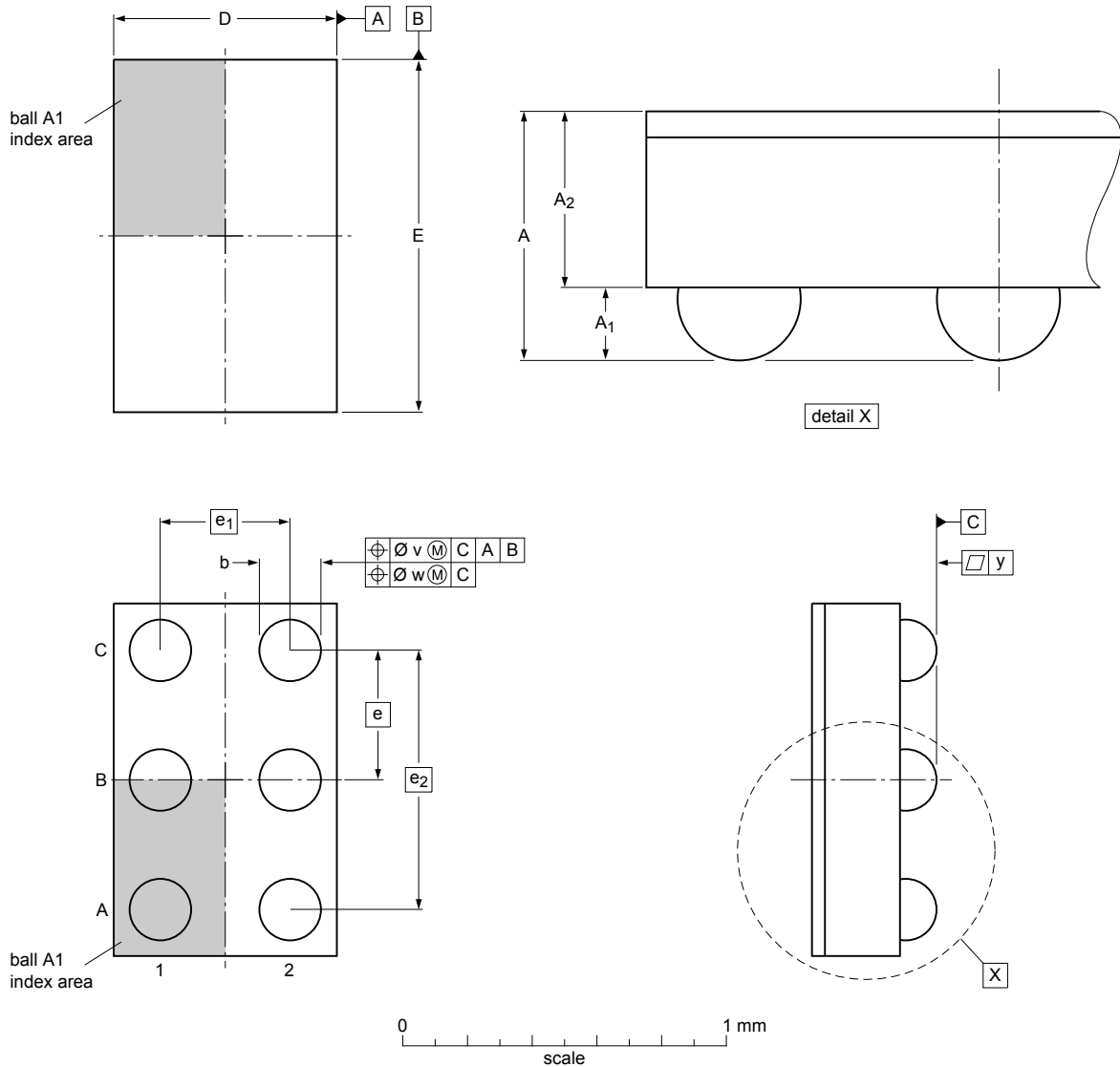
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.66	-	0.69	0.72	mm
E	package width	1.06	-	1.09	1.12	mm
A	seated height	0.35	-	0.38	0.41	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

WLCSP6: wafer level chip-scale package; 6 bumps; 0.69 x 1.09 x 0.38 mm (Backside coating included) PCT2202



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.41	0.125	0.287	0.22	0.72	1.12						
nom	0.38	0.110	0.272	0.19	0.69	1.09	0.4	0.4	0.8	0.15	0.05	0.05
min	0.35	0.095	0.257	0.16	0.66	1.06						

wlcspp6_pct2202_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
PCT2202	---	---	---		-13-10-07- 14-11-19

Fig. 1. Package outline WLCSP6 (OL-PCT2202)

wafer level chip-scale package; 6 bumps; 0.69 x 1.09 x 0.38 mm (Backside coating included)

3. Soldering

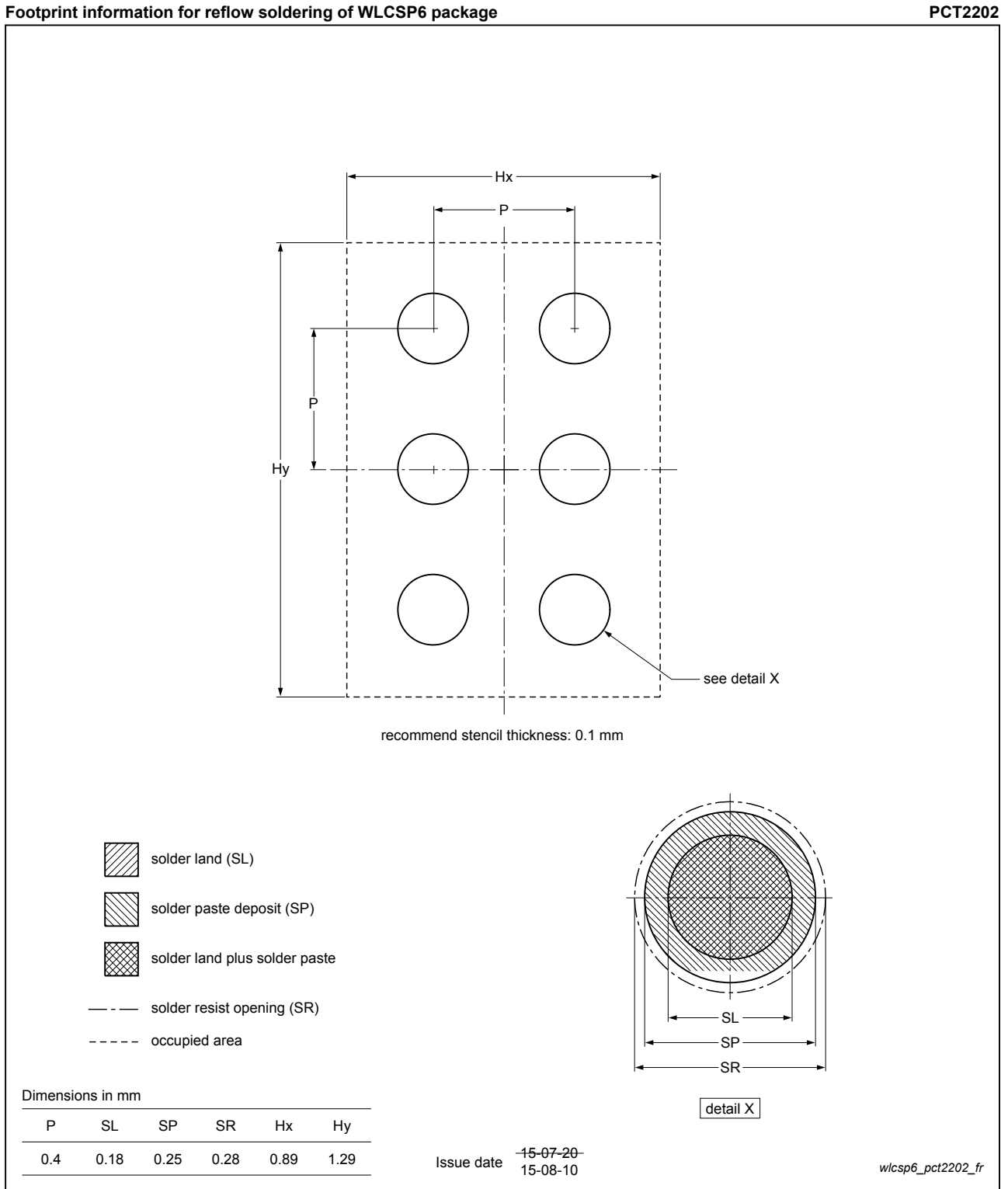


Fig. 2. Reflow soldering footprint for WLCSP6 (OL-PCT2202)

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4. Legal information

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